

Title (en)
Electrolytic copper plating method

Title (de)
Procédé de dépôt électrolytique de cuivre

Title (fr)
Verfahren zur elektrolytischen Kupferplattierung

Publication
EP 1741804 B1 20160427 (EN)

Application
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Priority
US 69783305 P 20050708

Abstract (en)
[origin: EP1741804A1] Copper plating baths containing a leveling agent that is a reaction product of a compound including a heteroatom chosen from nitrogen, sulfur and a mixture of nitrogen and sulfur, with a polyepoxide compound containing an ether linkage that deposit copper on the surface of an electronic device and in apertures on such substrate are provided. Such plating baths deposit a copper layer on the substrate surface that is substantially planar across a range of electrolyte concentrations. Methods of depositing copper layers using such copper plating baths are also disclosed.

IPC 8 full level
C25D 3/38 (2006.01)

CPC (source: EP KR US)
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